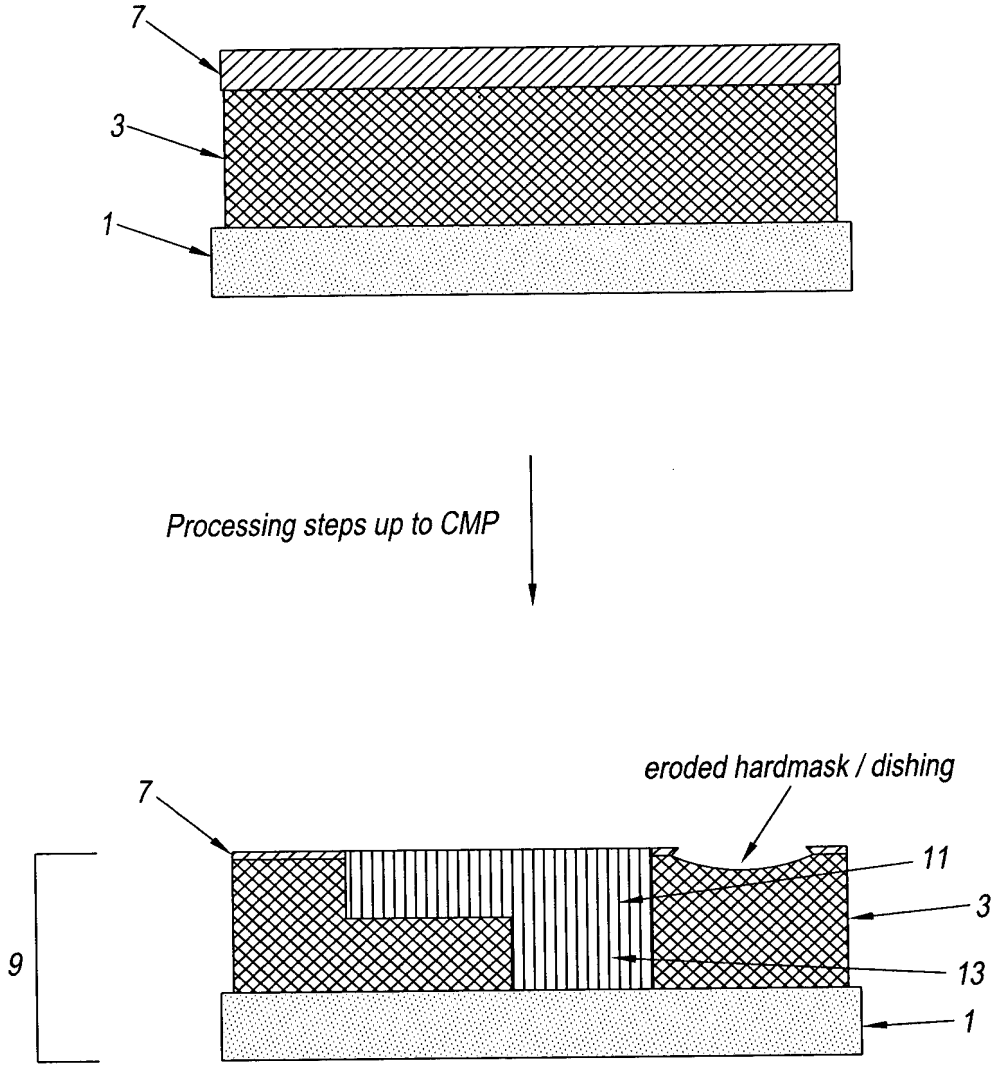
7
3
1
Processing steps up to CMP
eroded hardmask / dishing
7
11
3
9
13
1

FIG. 1

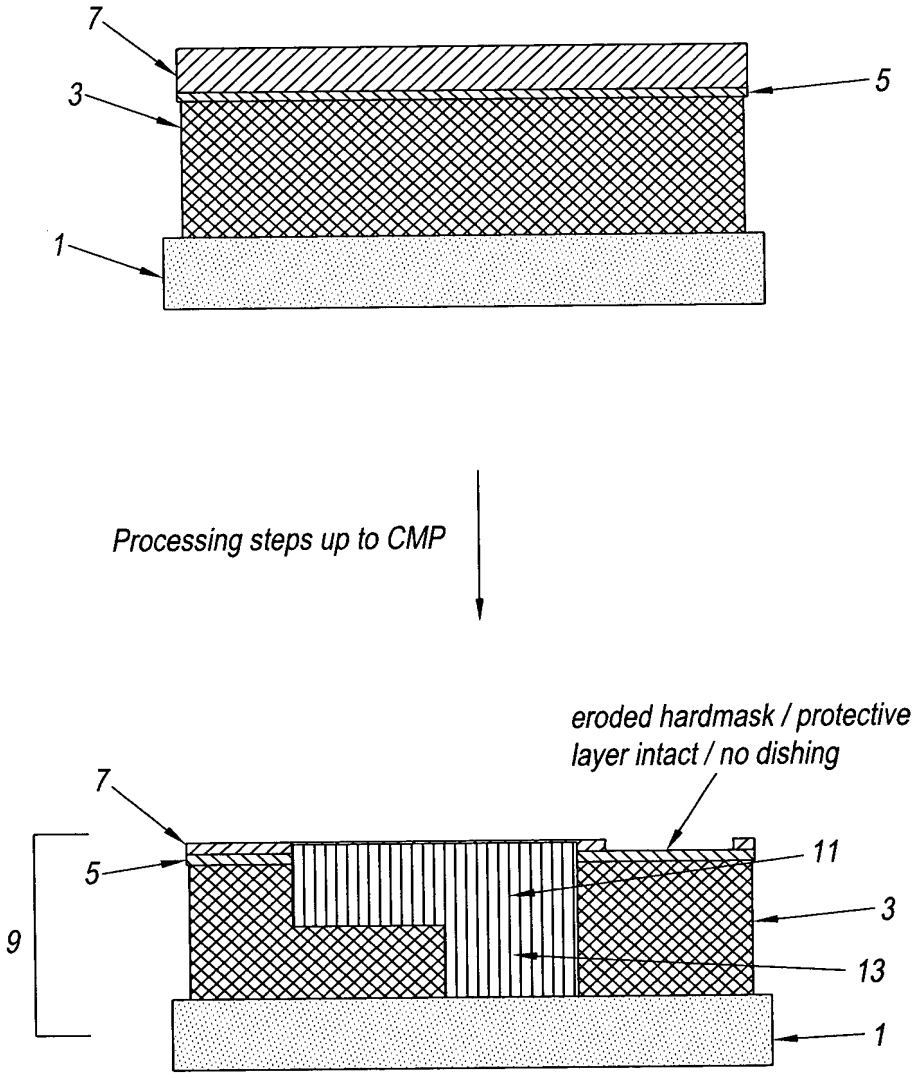
7
3
5
1
Processing steps up to CMP
eroded hardmask / protective layer intact / no dishing
7
5
9
11
3
13
1

FIG. 2

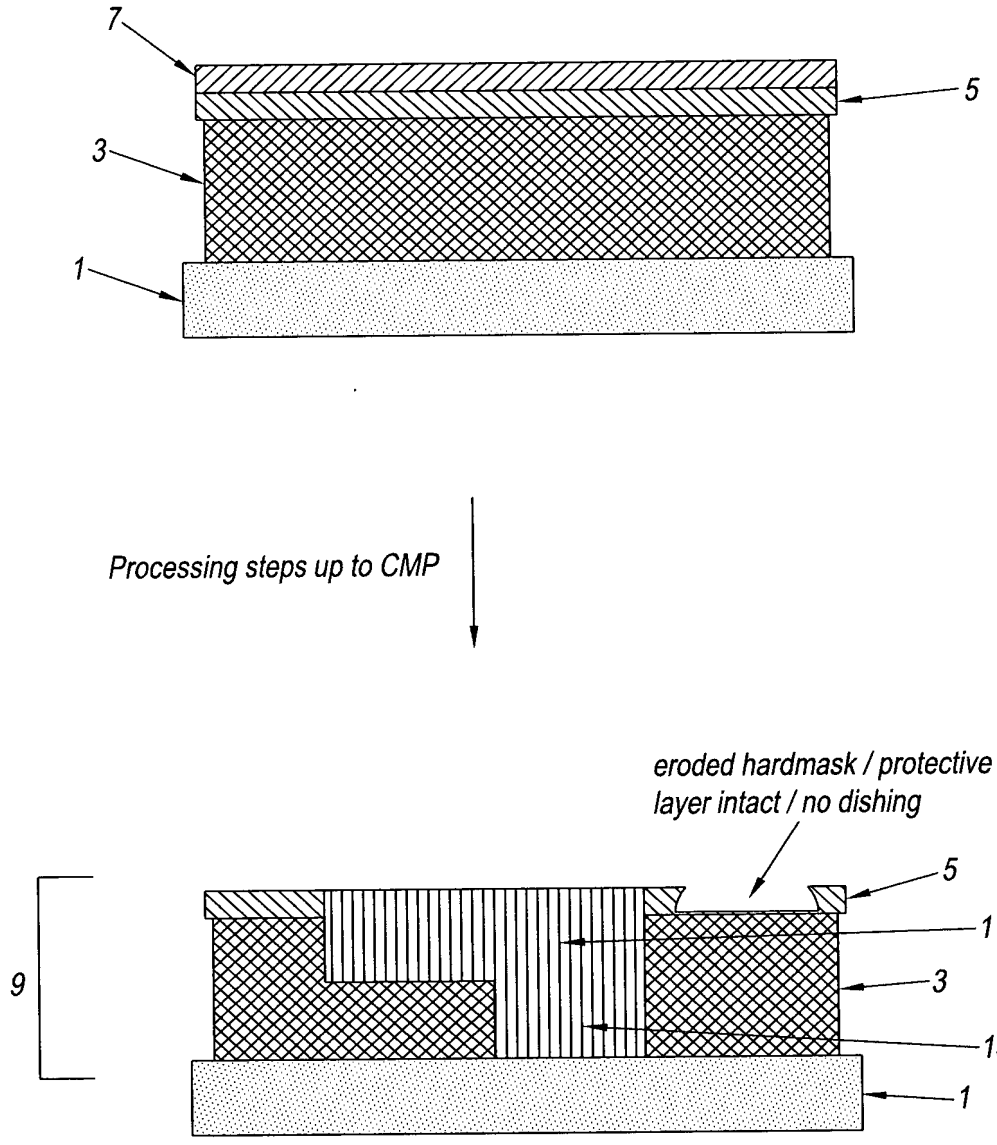
7
5
3
1
Processing steps up to CMP
eroded hardmask / protective
layer intact / no dishing
5
11
3
13
1
9

FIG. 3

1) Spin Dielectric layer or layers
2) Hot plate bake dielectric layer to crosslink (310°C, 2 min + 400°C, 2 min)
3) Spin CMP protective layer
4) Hot plate bake CMP protective layer (310°C, 2 min)
5) Furnace Cure multilayer stack (415°C, 1hr)
6) Deposit Hardmask / CMP polish stop layer by conventional CVD methods

FIG. 4